

**TM024GAD8**  
**1 048 576 BY 8-BIT**  
**DYNAMIC RAM MODULE**

SMMS108A — MARCH 1990 — REVISED NOVEMBER 1990

*This Data Sheet is Applicable to All TM024GAD8s Manufactured With TMS4C1024s Symbolized With Revision "D" and Subsequent Revisions.*

- **TM024GAD8 . . . 1 048 576 × 8 Organization**
- **Single 5-V Supply (10% Tolerance)**
- **30-Pin Single-In-Line Package (SIP)**  
— Leadless Module for Use With Sockets
- **Utilizes Eight 1-Megabit Dynamic RAMs in Plastic Small-Outline J-Lead (SOJ) Packages**
- **Long Refresh Period . . . 8 ms (512 Cycles)**
- **All Inputs, Outputs, Clocks Fully TTL Compatible**
- **3-State Output**
- **Performance of Unmounted RAMs:**

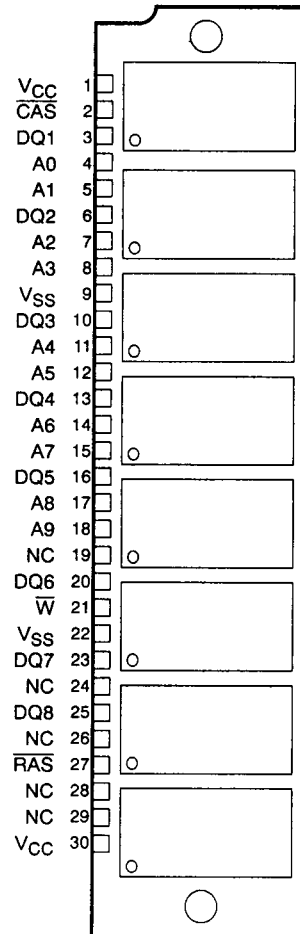
	ACCESS TIME	ACCESS TIME	READ OR WRITE CYCLE	V <sub>CC</sub> TOLERANCE
	t <sub>RAC</sub>	t <sub>CAC</sub>	(MIN)	
	(MAX)	(MAX)		
TMS4C1024-6	60 ns	15 ns	110 ns	5%
TMS4C1024-70	70 ns	18 ns	130 ns	10%
TMS4C1024-80	80 ns	20 ns	150 ns	10%
TMS4C1024-10	100 ns	25 ns	180 ns	10%

- **Common  $\overline{\text{CAS}}$  Control for Eight Common Data-In and Data-Out Lines**
- **Low Power Dissipation**
- **Operating Free Air Temperature . . . 0°C to 70°C**

**description**

The TM024GAD8 is a 8192K (dynamic) random-access memory module organized as 1 048 576 × 8 in a 30-pin single-in-line (SIP) module. The TM024GAD8 is composed of eight TMS4C1024DJ, 1 048 576 × 1-bit dynamic RAMs, each in 20/26-lead plastic small-outline J-lead packages (SOJ), mounted on a substrate together with decoupling capacitors.

**AD Single-In-Line Package (Top View)**



**PIN NOMENCLATURE**

A0-A9	Address Inputs
CAS	Column-Address Strobe
DQ1-DQ8	Data In/Data Out
NC	No Connection
RAS	Row-Address Strobe
V <sub>CC</sub>	5-V Supply
V <sub>SS</sub>	Ground
W	Write Enable

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The TMS4C1024DJ is described in its data sheet and is fully electrically tested and processed according to TI MIL-STD-883B flows (as amended for commercial applications) prior to assembly. After assembly onto the SIP, a further set of electrical tests is performed.

The TM024GAD8 SIP is available in the AD single-sided, leadless module for use with sockets.

The TM024GAD8 SIP is rated for operation from 0°C to 70°C.

**operation**

The TM024GAD8 operates as eight TMS4C1024DJs connected as shown in the functional block diagram. Refer to the TMS4C1024 data sheet for details of its operation. The common I/O feature of the TM024GAD8 dictates the use of early write cycles to prevent contention on D and Q.

**specifications**

For TMS4C1024DJ electrical specifications, refer to the TMS4C1024 data sheet.

**single-in-line package and components**

PC substrate: 1,27 (0.05 inch) nominal thickness; 0.005 inch/inch maximum warpage

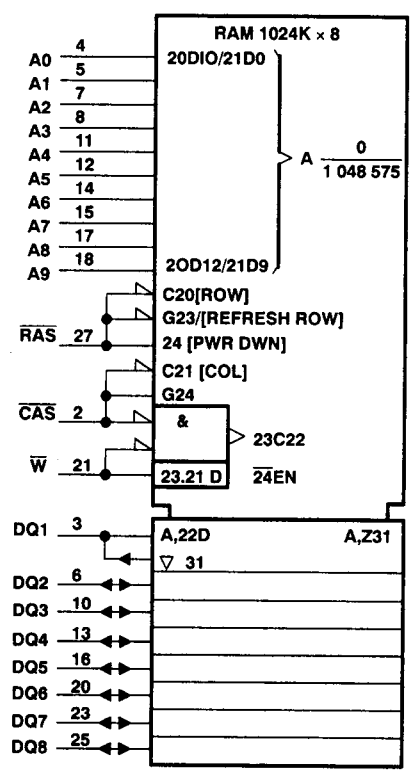
Bypass capacitors: Multilayer ceramic

Contact area for socketable devices: Nickel plate and solder plate (or coat) on top of copper

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logic symbol†

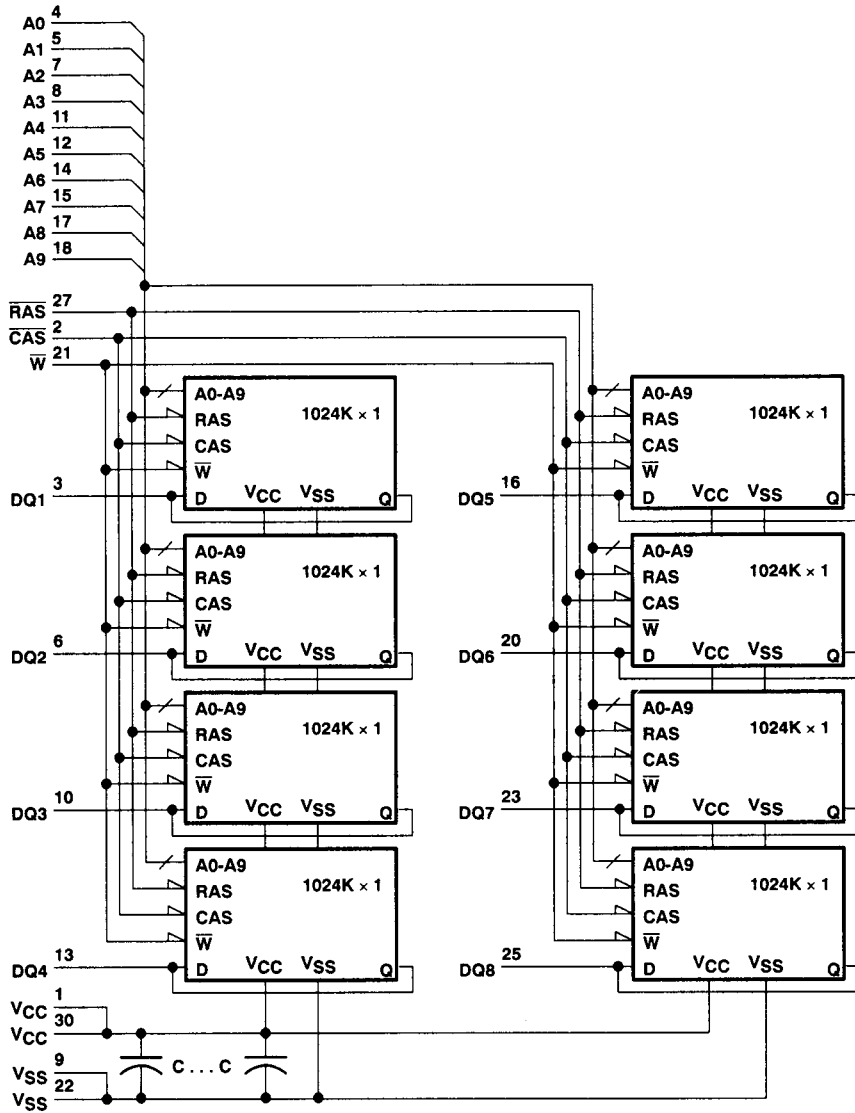


† This symbol is in accordance with ANSI/IEEE Std. 9-1084 and IEC Publication 617-12.

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**functional block diagram**



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**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Voltage range on any pin (see Note 1)	.....	- 1 V to 7 V
Voltage range on V <sub>CC</sub> (see Note 1)	.....	- 1 V to 7 V
Short circuit output current	.....	50 mA
Power dissipation	.....	8 W
Operating free-air temperature range	.....	0°C to 70°C
Storage temperature range	.....	- 65°C to 150°C

† Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the "Recommended Operating Conditions" section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values in this data sheet are with respect to V<sub>SS</sub>.

**recommended operating conditions**

	MIN	NOM	MAX	UNIT
V <sub>CC</sub> Supply voltage (TM024GAD8-6)	4.75	5	5.25	V
V <sub>CC</sub> Supply voltage (TM024GAD8-70/-80/-10)	4.5	5	5.5	V
V <sub>IH</sub> High-level input voltage	2.4		6.5	V
V <sub>IL</sub> Low-level input voltage (see Note 2)	-1		0.8	V
T <sub>A</sub> Operating free-air temperature	0		70	°C

NOTE 2: The algebraic convention, where the more negative (less positive) limit is designated as minimum, is used in this data sheet for logic voltage levels only.

**electrical characteristics over full ranges of recommended operating conditions (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	TM024GAD8-6		TM024GAD8-70		TM024GAD8-80		TM024GAD8-10		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub> High-level output voltage	I <sub>OH</sub> = - 5 mA	2.4		2.4		2.4		2.4		V
V <sub>OL</sub> Low-level output voltage	I <sub>OL</sub> = 4.2 mA		0.4		0.4		0.4		0.4	V
I <sub>I</sub> Input current (leakage)	V <sub>I</sub> = 0 to 6.5 V, V <sub>CC</sub> = 5.5 V, All other pins = 0 V to V <sub>CC</sub>		± 10		± 10		± 10		± 10	µA
I <sub>O</sub> Output current (leakage)	V <sub>O</sub> = 0 to V <sub>CC</sub> , V <sub>CC</sub> = 5.5 V, CAS high		± 10		± 10		± 10		± 10	µA
I <sub>CC1</sub> Read or write cycle current	Minimum cycle, V <sub>CC</sub> = 5.5 V		760		640		600		520	mA
I <sub>CC2</sub> Standby current	After 1 memory cycle, RAS and CAS high, V <sub>IH</sub> = 2.4 V		16		16		16		16	mA
I <sub>CC3</sub> Average refresh current (RAS-only or CBR)	Minimum cycle, V <sub>CC</sub> = 5.5 V, RAS cycling, CAS high (RAS-only), RAS low after CAS low (CBR)		720		640		560		480	mA
I <sub>CC4</sub> Average page current	t <sub>c(P)</sub> = minimum, V <sub>CC</sub> = 5.5 V, RAS low, CAS cycling		560		480		400		360	mA

**capacitance over recommended ranges of supply voltage and operating free-air temperature, f = 1 MHz (see Note 3)**

PARAMETER	MIN	MAX	UNIT
C <sub>i(A)</sub> Input capacitance, address inputs		40	pF
C <sub>i(RC)</sub> Input capacitance, strobe inputs		40	pF
C <sub>i(W)</sub> Input capacitance, write-enable input		40	pF
C <sub>O</sub> Output capacitance (DQ1-DQ8)		10	pF

NOTE 3: V<sub>CC</sub> equal to 5 V ± 0.5 V and the bias on pins under test is 0 V.



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**TI single-in-line package nomenclature**

